

Fiberglass Thermal Pad

Super soft single side silicon tape enhanced thermal conductive pad. The product has excellent mechanical properties and insulation performance; ultra-low hardness, good resilience and high compression ratio, is applicable to large institutional design of tolerance. Because of its low hardness, it has smaller thermal resistance in the case of low pressure, eliminate the air between the components and circuit boards, and full fill all kinds of rough surface at the same time. By special ultra-thin glass fiber cloth double-layer structure, increase the operability and durability, it will not be broken and deformation when stamping, punching or deformity design

Features

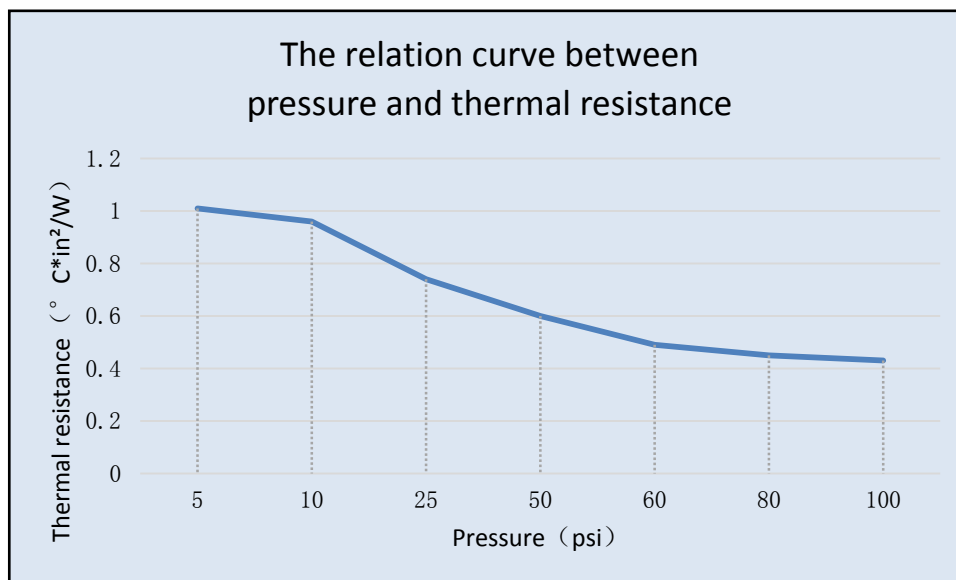
- Super soft, high-pressure shrank, high deformation
- Fiberglass reinforced for puncture, shear and tear resistance
- Easy release construction
- Electrically isolating



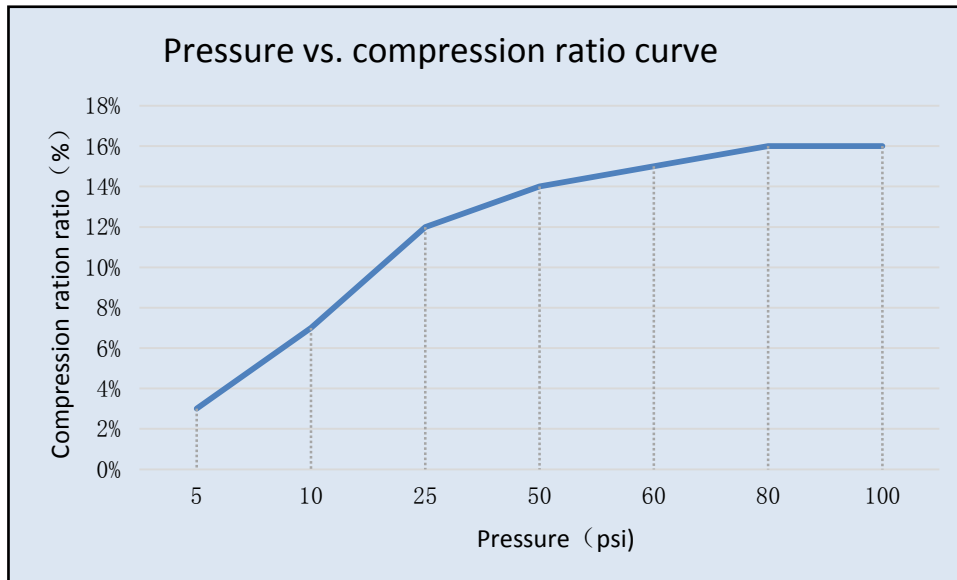
Specification

Colour	Dark Red	
Thermal Impedance @1mm/20Psi	550 mW/°C	ASTM D5470
Specific Gravity	2 g/cm ³	ASTM D792
Volume Resistivity	10 ¹⁴ ΩCM	ASTM D257
Thermal Conductivity	1.2 W/mk	ASTM D5470
Dielectric Constant @1MHz	5.5	ASTM D150
Hardness	20-25 Shore 00	ASTM D2240
Flammability Class	UL94-V0	UL94
Working Temperature	-50 ... 200 °C	
Self-Adhesive	Single side self-seal	

Test Method



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Art Nr.	Dimensions
RND 460-00123	100 x 100 x 1 mm
RND 460-00124	100 x 100 x 2 mm
RND 460-00130	100 x 100 x 0.5 mm
RND 460-00136	100 x 100 x 3.2 mm
RND 460-00140	100 x 100 x 5.1 mm